

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

1-32. (Cancelled)

33. (Currently amended) A circuit substrate comprising:

a substrate including a first surface and a second surface opposite to the first surface;

a first conductor pattern formed on the first surface; [[and]]

a second conductor pattern formed on the second surface;

an external terminal formed on the second conductor pattern to mount the circuit

substrate on a second substrate;

a dielectric layer formed on the second conductor pattern and the second surface; and

a third conductor pattern formed on the dielectric layer and the second surface,

~~wherein the first surface is adapted for mounting a device smaller than the substrate,~~

~~the second surface is adapted for mounting to a second substrate, and~~

the second surface has larger surface roughness than the first surface,

the dielectric layer covers the edge of the second conductor pattern,

the third conductor pattern covers the edge of the second conductor pattern through the

dielectric layer, and

the second conductor pattern, the dielectric layer and the third conductor pattern form a

capacitor.

34-35. (Cancelled)

36. (Previously presented) A circuit substrate according to claim 34, wherein the external terminal is a ball-shaped solder.

37. (Previously presented) A circuit substrate according to claim 33, further comprising a through hole in the substrate connecting the first and second surface.

38. (Previously presented) A circuit substrate according to claim 37, further comprising an electrode filled in the through hole.

39. (Previously presented) A circuit substrate according to claim 37, further comprising an electrode formed along the through hole.

40. (Previously presented) A circuit substrate according to claim 38, wherein the external terminal is connected directly underneath the electrode.

41. (Previously presented) A circuit substrate according to claim 39, further comprising a solder filled in the through hole.

42. (Previously presented) A circuit substrate according to claim 41, wherein the solder has a higher melting point than the external terminal.

43-53. (Cancelled)

54. (Previously presented) A circuit substrate according to claim 33, further comprising an electrode filled in a through hole of the substrate,

wherein the electrode connects the first conductor pattern with the second conductor pattern, and

the second conductor pattern covers the electrode on the second surface and includes the same metal as the electrode.